## imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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PoHS compliant.	2011/65/EJ		11.70	NOTES:			A
<u>1.00</u> <u>8.00</u> <u>5-0.</u> <u>4-0.30</u>	40 40 40	<u></u>		1. MATERIAL: HOUSING: HIGH TEMPERAT 30% GLASS FIE TERMINAL: PHOSPHOR BR SHELL: SPCC	URE THERMAL PLASTIC, LCI BER FILLED, COLOR: BLUE 3 ONZE.	P , UL94V-0, 300C	
		0.80	3.05	2. FINISH: TERMINAL: CONTACT AREA: GOLD SOLDERING AREA: MATT	PLATING 30 μ" THICKNES: ΓΕ ΤΙΝ PLATING 100 μ" TI L PLATING 50 μ" THICKNE	HICKNESS MIN.;	В
20.65±0.30	70±0.15			SHELL: NICKEL PLATING 50 $\mu$ " 3. PRODUCT SPECIFICATION I 4. THIS PRODUCT IS LEAD-F	MINIMUM OVERALL, REFER TO : PS-7425		
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01.070 05.07 05.07 12.00±0.10	10.05			PART NO. GSB3164X1CEU PCB EI 0.90 PLATING OF 2 PLC	DGE	01.20 2 PLC 52	
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e //>	/	SECTION A-A		RECOMME	ND P.C.B LAYOUT GERE (COMPONENT SI		<u>5</u>
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		ANGULAR ±1°	Arron Lin T <sup>ype</sup> CUST DWG	08/06/2015 PPRUEET CODE OTHER	SIZE A.3 PART No. SHEET OF 2 DVG No.	GSB3164X1CEU	
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